

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-803: Skúšobné metódy na rozpínanie základných druhov materiálov a dosiek s plošnými spojmi v osi Z	STN EN IEC 61189-2-803 34 6513
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-803: Test methods for Z-axis expansion of base materials and printed boards

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/23

Obsahuje: EN IEC 61189-2-803:2023, IEC 61189-2-803:2023

137671

EUROPEAN STANDARD

EN IEC 61189-2-803

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2023

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 2-803: Test
methods for Z-axis expansion of base materials and printed
boards
(IEC 61189-2-803:2023)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-803: Méthodes d'essai pour la
dilatation suivant l'axe Z des matériaux de base et des
cartes imprimées
(IEC 61189-2-803:2023)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 2-
803: Prüfverfahren für die Z-Achsen-Ausdehnung von
Basismaterialien und Leiterplatten
(IEC 61189-2-803:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-803:2023 (E)**European foreword**

The text of document 91/1760/CDV, future edition 1 of IEC 61189-2-803, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-803:2023.

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Annex ZA (normative)

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-



IEC 61189-2-803

Edition 1.0 2023-07

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 2-803: Test methods for Z-axis expansion of base materials and printed boards**

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 2-803: Méthodes d'essai pour la dilatation suivant l'axe Z des matériaux de base et des cartes imprimées**



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IEC 61189-2-803

Edition 1.0 2023-07

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INTERNATIONAL
ELECTROTECHNICAL
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COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.180

ISBN 978-2-8322-7264-0

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CONTENTS

FOREWORD	3
1 Scope	5
2 Normative references	5
3 Terms and definitions	5
4 Preparation of test specimens	5
5 Test specimens	5
6 Test apparatus	6
7 Test procedure	6
8 Calculation	6
9 Report	7
Bibliography.....	8
Figure 1 – Example TMA data output	6

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-803: Test methods for Z-axis expansion of base materials and
printed boards**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1760/CDV	91/1863/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

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- withdrawn,
- replaced by a revised edition, or
- amended.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-803: Test methods for Z-axis expansion of base materials and printed boards

1 Scope

This part of IEC 61189 specifies a test method to determine the Z-axis expansion of base materials and printed boards using a thermomechanical analyser (TMA).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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